

EL 465852697

EL 373341542
DECLARATION OF SOLE INVENTOR FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: Board-On-Chip Packages, and Methods of Forming Board-On-Chip Packages, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so

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made are punishable by fine or imprisonment, or both, under
Section 1001 of Title 18 of the United States Code and that such willful
false statement may jeopardize the validity of the application or any
patent issued therefrom.

* * * * *

Full name of sole inventor: **Salman Akram**

Inventor's Signature: Salman Akram

Date: Sept 1st 99

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Citizenship: **Pakistan**

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